

FEATURES

- Member of the Texas Instruments Widebus+™ Family
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DESCRIPTION/ORDERING INFORMATION

This device contains eight independent noninverting buffers and a 16-bit noninverting bus transceiver and D-type latch designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVCH32973 is particularly suitable for demultiplexing an address/data bus into a dedicated address bus and dedicated data bus. The device is used where there is asynchronous bidirectional communication between the A and B data bus, and the address signals are latched and buffered on the Q bus. The control-function implementation minimizes external timing requirements.

This device can be used as one 8-bit buffer, two 8-bit transceivers, and two 8-bit latches or one 8-bit buffer, one 16-bit transceiver, and one 16-bit latch. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The transceiver output-enable (\overline{TOE}) input can be used to disable the transceivers so that the A and B buses effectively are isolated.

When the latch-enable (LE) input is high, the Q outputs follow the data (A) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the A inputs. The latch output-enable (\overline{LOE}) input can be used to place the nine Q outputs in either a normal logic state (high or low logic level) or the high-impedance state. In the high-impedance state, the Q outputs neither drive nor load the bus lines significantly. \overline{LOE} does not affect internal operations of the latch. Old data can be retained or new data can be entered while the Q outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{LOE} and \overline{TOE} should be tied to V_{CC} through pullup resistors; the minimum values of the resistors are determined by the current-sinking capability of the drivers.

The eight independent noninverting buffers perform the Boolean function $Y = D$ and are independent of the state of DIR, \overline{TOE} , LE, and \overline{LOE} .

The A and B I/Os and D inputs have bus-hold circuitry. Active bus-hold circuitry holds unused or undriven data inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

ORDERING INFORMATION

T_A	PACKAGE (1)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	LFBGA - GKE	Tape and reel	SN74ALVCH32973KR	ACH973
	LFBGA - ZKE (Pb-free)		74ALVCH32973ZKER	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



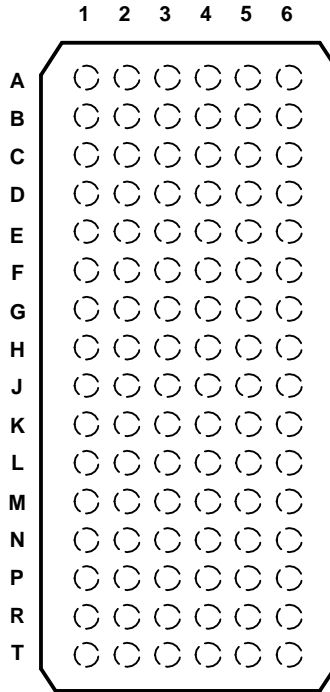
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus+ is a trademark of Texas Instruments.

SN74ALVCH32973
16-BIT BUS TRANSCEIVER AND TRANSPARENT D-TYPE LATCH
WITH EIGHT INDEPENDENT BUFFERS

SCES436C–APRIL 2003–REVISED SEPTEMBER 2004

GKE OR ZKE PACKAGE
(TOP VIEW)



TERMINAL ASSIGNMENTS

	1	2	3	4	5	6
A	1A1	D1	1 \overline{TOE}	1DIR	1B1	1Q1
B	1A2	Y1	GND	GND	1B2	1Q2
C	1A3	D2	V _{CC}	V _{CC}	1B3	1Q3
D	1A4	Y2	GND	GND	1B4	1Q4
E	1A5	D3	GND	GND	1B5	1Q5
F	1A6	Y3	V _{CC}	V _{CC}	1B6	1Q6
G	1A7	D4	GND	GND	1B7	1Q7
H	1A8	Y4	1LE	1 \overline{LOE}	1B8	1Q8
J	2A1	D5	2 \overline{TOE}	2DIR	2B1	2Q1
K	2A2	Y5	GND	GND	2B2	2Q2
L	2A3	D6	V _{CC}	V _{CC}	2B3	2Q3
M	2A4	Y6	GND	GND	2B4	2Q4
N	2A5	D7	GND	GND	2B5	2Q5
P	2A6	Y7	V _{CC}	V _{CC}	2B6	2Q6
R	2A7	D8	GND	GND	2B7	2Q7
T	2A8	Y8	2LE	2 \overline{LOE}	2B8	2Q8

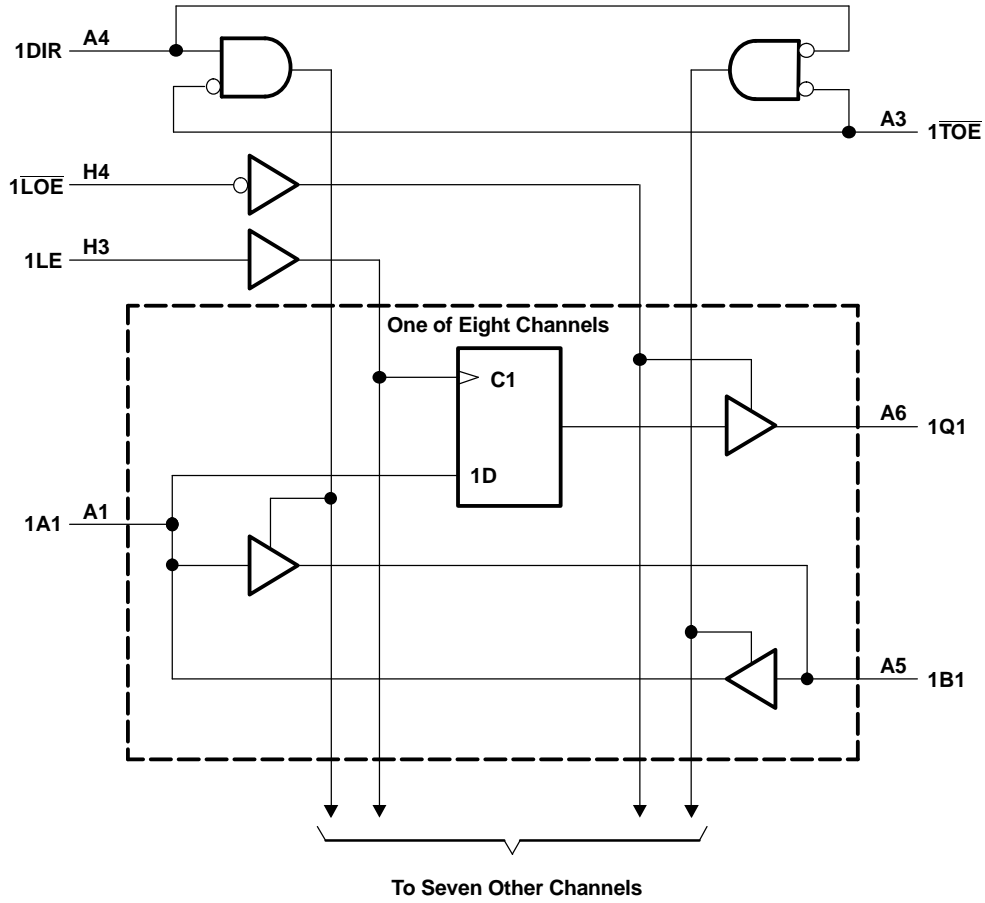
FUNCTION TABLES

INPUTS		OPERATION
\overline{TOE}	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	A bus and B bus isolation

INPUTS			OUTPUT Q
\overline{LOE}	LE	A	
L	H	H	H
L	H	L	L
L	L	X	Q ₀
H	X	X	Z

INPUT D	OUTPUT Y
L	L
H	H

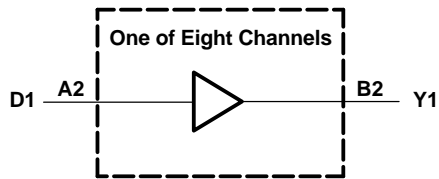
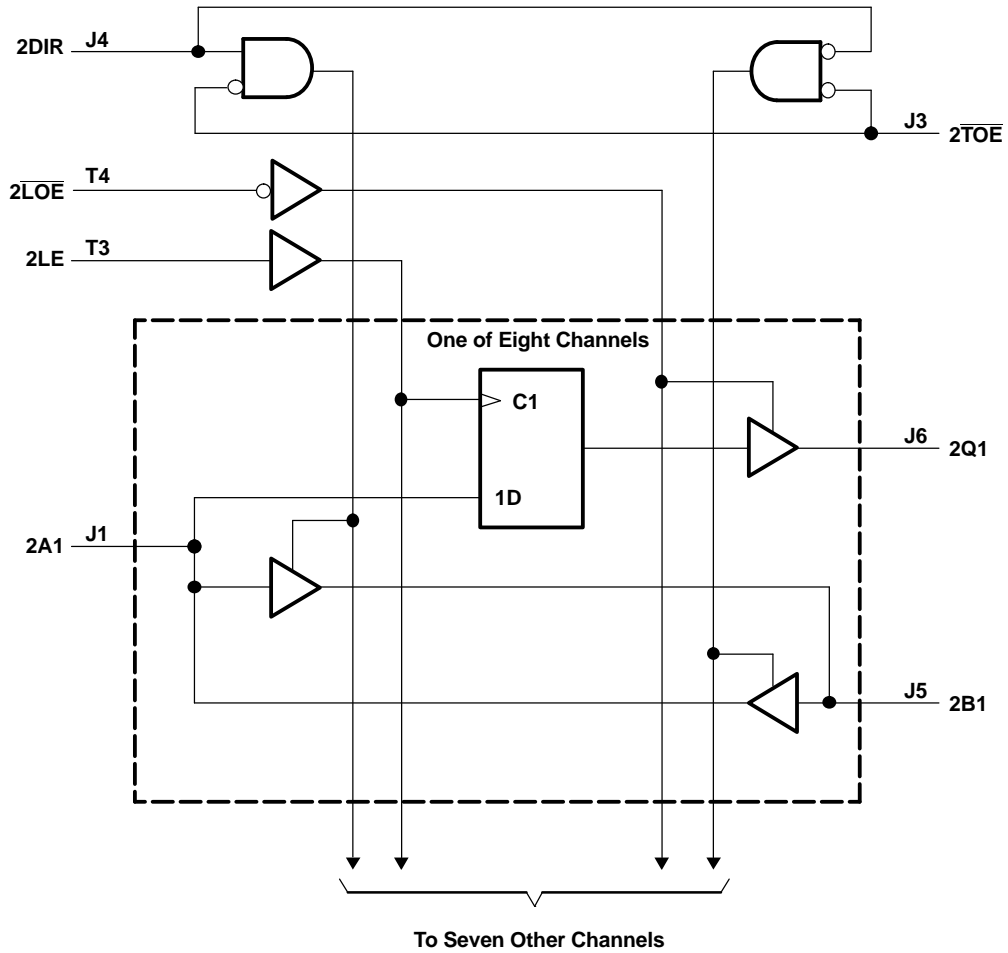
LOGIC DIAGRAM (POSITIVE LOGIC)



SN74ALVCH32973
16-BIT BUS TRANSCEIVER AND TRANSPARENT D-TYPE LATCH
WITH EIGHT INDEPENDENT BUFFERS

SCES436C—APRIL 2003—REVISED SEPTEMBER 2004

LOGIC DIAGRAM (POSITIVE LOGIC)



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT	
V _{CC}	Supply voltage range	-0.5	4.6	V	
V _I	Input voltage range	Except I/O and D input ports ⁽²⁾		V	
		I/O and D input ports ⁽²⁾⁽³⁾			
V _O	Output voltage range ⁽²⁾⁽³⁾	-0.5	V _{CC} + 0.5	V	
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
I _O	Continuous output current			±50	mA
	Continuous current through each V _{CC} or GND			±100	mA
θ _{JA}	Package thermal impedance ⁽⁴⁾	GKE/ZKE package		40	°C/W
T _{stg}	Storage temperature range	-65	150	°C	

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 4.6 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage	1.65	3.6	V
V _{IH}	High-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	1.7	
		V _{CC} = 3 V to 3.6 V	2	
V _{IL}	Low-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.35 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	0.7	
		V _{CC} = 3 V to 3.6 V	0.8	
V _I	Input voltage	0	V _{CC}	V
V _O	Output voltage	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 1.65 V	-4	mA
		V _{CC} = 2.3 V	-12	
		V _{CC} = 2.7 V	-12	
		V _{CC} = 3 V	-24	
I _{OL}	Low-level output current	V _{CC} = 1.65 V	4	mA
		V _{CC} = 2.3 V	12	
		V _{CC} = 2.7 V	12	
		V _{CC} = 3 V	24	
Δt/Δv	Input transition rise or fall rate		10	ns/V
T _A	Operating free-air temperature	-40	85	°C

- (1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74ALVCH32973

16-BIT BUS TRANSCEIVER AND TRANSPARENT D-TYPE LATCH WITH EIGHT INDEPENDENT BUFFERS

SCES436C–APRIL 2003–REVISED SEPTEMBER 2004

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{OH}	I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} - 0.2			V
	I _{OH} = -4 mA	1.65 V	1.2			
	I _{OH} = -6 mA	2.3 V	2			
	I _{OH} = -12 mA	2.3 V	1.7			
		2.7 V	2.2			
		3 V	2.4			
I _{OH} = -24 mA	3 V	2				
V _{OL}	I _{OL} = 100 μA	1.65 V to 3.6 V	0.2			V
	I _{OL} = 4 mA	1.65 V	0.45			
	I _{OL} = 6 mA	2.3 V	0.4			
	I _{OL} = 12 mA	2.3 V	0.7			
		2.7 V	0.4			
	I _{OL} = 24 mA	3 V	0.55			
I _I	V _I = V _{CC} or GND	3.6 V	±5			μA
I _{BHL} ⁽²⁾	V _I = 0.57 V	1.65 V	25			μA
	V _I = 0.7 V	2.3 V	45			
	V _I = 0.8 V	3 V	75			
I _{BHH} ⁽³⁾	V _I = 1.07 V	1.65 V	-25			μA
	V _I = 1.7 V	2.3 V	-45			
	V _I = 2 V	3 V	-75			
I _{BHLO} ⁽⁴⁾	V _I = 0 to V _{CC}	1.95 V	200			μA
		2.7 V	300			
		3.6 V	500			
I _{BHHO} ⁽⁵⁾	V _I = 0 to V _{CC}	1.95 V	-200			μA
		2.7 V	-300			
		3.6 V	-500			
I _{OZ} ⁽⁶⁾	V _O = V _{CC} or GND	3.6 V	±10			μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	3.6 V	60			μA
ΔI _{CC}	One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V	750			μA
C _i	Control inputs	V _I = V _{CC} or GND	3			pF
	D					
C _{io}	A ports	V _O = V _{CC} or GND	3.3 V			pF
	B ports					
C _o	Q	V _O = V _{CC} or GND	3.3 V			pF

- (1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.
- (2) The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.
- (3) The bus-hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.
- (4) An external driver must source at least I_{BHLO} to switch this node from low to high.
- (5) An external driver must sink at least I_{BHHO} to switch this node from high to low.
- (6) For I/O ports, the parameter I_{OZ} includes the input leakage current.

TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		$V_{CC} = 1.8\text{ V}$		$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high	2		2		2		ns
t_{su}	Setup time, data before LE↓	0.9		0.9		0.9		ns
t_h	Hold time, data after LE↓	0.9		0.9		0.9		ns

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8\text{ V}$		$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			TYP		MIN	MAX	MIN	MAX	
t_{pd}	D	Y	2.2		0.5	3.2	0.5	3	ns
	A	Q	2.2		0.5	3.2	0.5	3	
	LE		2.8		0.5	3.3	0.5	3	
	A or B	B or A	2.2		0.5	3.2	0.5	3	
t_{en}	\overline{LOE}	Q	2.9		0.7	4.9	0.7	4.7	ns
	\overline{TOE}	A or B	3		0.7	4.6	0.7	4.4	
	DIR		3.4		0.7	4.9	0.7	4.7	
t_{dis}	\overline{LOE}	Q	2.8		0.5	4.3	0.5	4.1	ns
	\overline{TOE}	A or B	3.2		0.5	4.3	0.5	4.1	
	DIR		3.4		0.5	4.9	0.5	4.7	

SN74ALVCH32973
16-BIT BUS TRANSCEIVER AND TRANSPARENT D-TYPE LATCH
WITH EIGHT INDEPENDENT BUFFERS

SCES436C–APRIL 2003–REVISED SEPTEMBER 2004

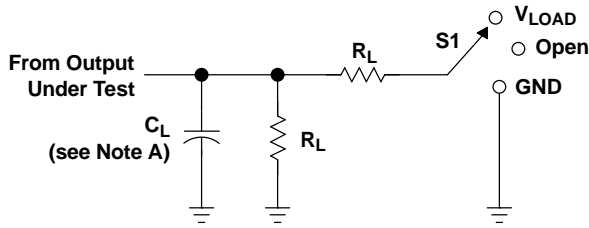
OPERATING CHARACTERISTICS⁽¹⁾

T_A = 25°C

PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	UNIT
			TYP	TYP	TYP	
C _{pd} ⁽²⁾ (each output)	Power dissipation capacitance	A outputs enabled, Q outputs disabled, one A output switching One f _A = 10 MHz, One f _B = 10 MHz, TOE = GND, LOE = V _{CC} , DIR = GND, C _L = 0 pF	12	14	19	pF
		B outputs enabled, Q outputs disabled, one B output switching One f _A = 10 MHz, One f _B = 10 MHz, TOE = GND, LOE = V _{CC} , DIR = GND, C _L = 0 pF	12	14	21	
		Q outputs enabled, A and B I/Os isolated, one Q output switching One f _A = 10 MHz, One f _{LE} = 20 MHz, One f _Q = 10 MHz, TOE = V _{CC} , LOE = GND, C _L = 0 pF	11	13	19	
		One Y output switching, A and B I/Os isolated, Q outputs disabled One f _D = 10 MHz, One f _Y = 10 MHz, TOE = V _{CC} , LOE = V _{CC} , C _L = 0 pF	7	8	12	
C _{pd} ^(Z)	Power dissipation capacitance	A and B I/Os isolated, Q outputs disabled, one LE and one A data input switching One f _A = 10 MHz, One f _{LE} = 20 MHz, f _Q not switching, TOE = V _{CC} , LOE = V _{CC} , C _L = 0 pF	4	5	11	pF
C _{pd} ⁽³⁾ (each LE)	Power dissipation capacitance	A and B I/Os isolated, Q outputs disabled, one LE input switching f _A not switching, One f _{LE} = 20 MHz, f _Q not switching, TOE = V _{CC} , LOE = V _{CC} , C _L = 0 pF	6	7	9	pF

- (1) Total device C_{pd} for multiple (m) outputs switching and (n) LE inputs switching = [m * C_{pd} (each output)] + [n * C_{pd} (each LE)]
(2) C_{pd} (each output) is the C_{pd} for each data bit (input and output circuitry) when it operates at 10 MHz (Note: The LE is operating at 20 MHz in this test, but its I_{CC} component has been subtracted).
(3) C_{pd} (each LE) is the C_{pd} for the clock circuitry only when it operates at 20 MHz.

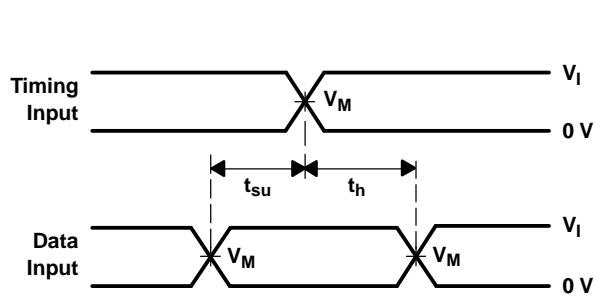
PARAMETER MEASUREMENT INFORMATION



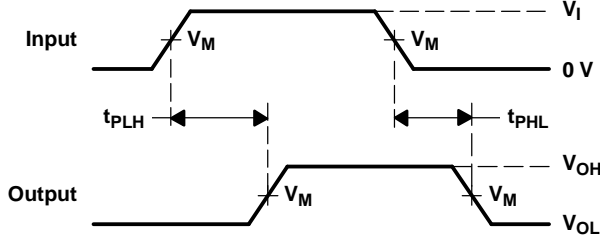
TEST	S1
t_{pd} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open V_{LOAD} GND

LOAD CIRCUIT

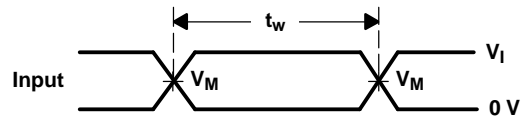
V_{CC}	INPUT		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_r/t_f					
1.8 V	V_{CC}	≤ 2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5 V \pm 0.2 V$	V_{CC}	≤ 2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
$3.3 V \pm 0.3 V$	2.7 V	≤ 2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



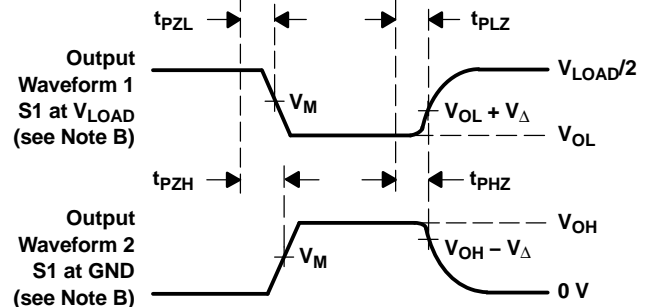
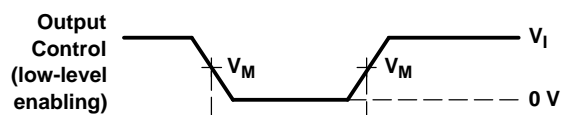
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ALVCH32973ZKER	ACTIVE	LFBGA	ZKE	96	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR
SN74ALVCH32973KR	ACTIVE	LFBGA	GKE	96	1000	TBD	SNPB	Level-2-235C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ALVCH32973ZKER	LFBGA	ZKE	96	1000	330.0	24.4	5.7	13.7	2.0	8.0	24.0	Q1
SN74ALVCH32973KR	LFBGA	GKE	96	1000	330.0	24.4	5.7	13.7	2.0	8.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

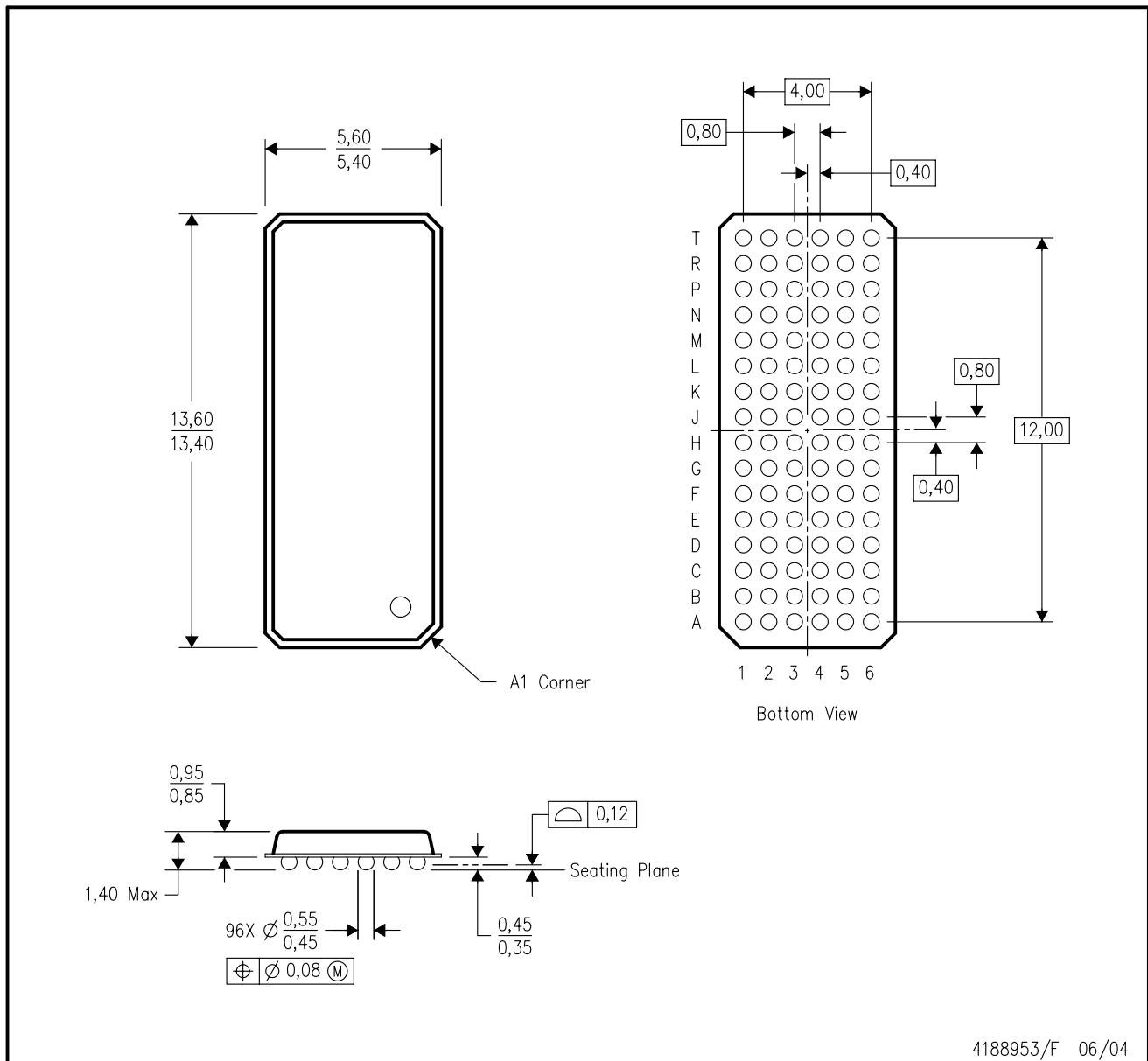


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ALVCH32973ZKER	LFBGA	ZKE	96	1000	333.2	345.9	31.8
SN74ALVCH32973KR	LFBGA	GKE	96	1000	333.2	345.9	31.8

GKE (R-PBGA-N96)

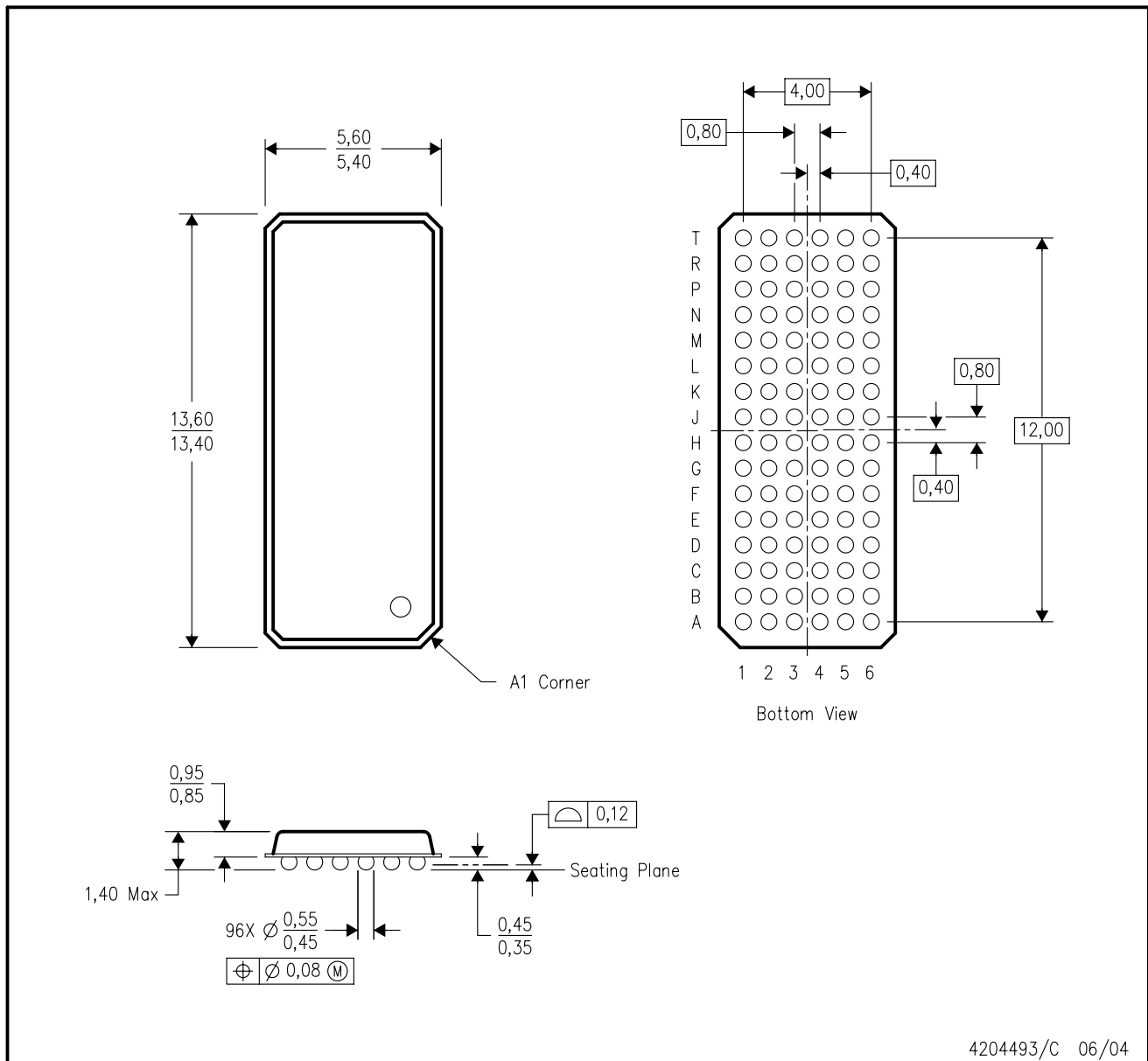
PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-205 variation CC.
 - D. This package is tin-lead (SnPb). Refer to the 96 ZKE package (drawing 4204493) for lead-free.

ZKE (R-PBGA-N96)

PLASTIC BALL GRID ARRAY



4204493/C 06/04

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-205 variation CC.
 - D. This package is lead-free. Refer to the 96 GKE package (drawing 4188953) for tin-lead (SnPb).

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Transportation and Automotive	www.ti.com/automotive
Video and Imaging	www.ti.com/video
Wireless	www.ti.com/wireless-apps

TI E2E Community Home Page

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2011, Texas Instruments Incorporated